

## Surface-Mount Devices | 1206 Size

### SRF1206 Series

## **PTC Resettable Fuses**

#### **Features**

- Resettable over current and over temperature protection
- Small size of 1206
- Fast time-to-trip
- Small footprint
- RoHS complaint
- Low resistance







## **Applications**

- Computer
- Portable electronics
- Multimedia
- Game machines
- Telephony and broadband
- Mobile phones
- Battery
- Industrial controls



#### **Electrical Characteristics**

	$I_{H}$	$I_{T}$	$V_{max}$	$I_{max}$	Time	to Trip	$Pd_{typ}$	$R_{min}$	$R1_{\text{max}}$
Part Number	(A)	(A)	(V)	(A)	(A)	(Sec.)	(W)	$(\Omega)$	$(\Omega)$
SRF1206P075/16	0.75	1.50	16	100	8.0	0.20	0.6	0.09	0.50

R1<sub>max</sub> = Maximum resistance of device at 25 °C measured one hour after reflow soldering

Value specified is determined by using the PWB with 0.030" \*1.5oz copper traces. Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

## Thermal Derating Chart Hold Current (A)

Part Number	Ambient Operating Temperature								
Part Number	<b>-40</b> °C	<b>-20</b> °C	<b>0</b> °C	<b>25</b> °C	<b>40</b> °C	<b>50</b> °C	<b>60</b> °C	<b>70</b> °C	<b>85</b> °C
SRF1206P075/16	1.14	1.01	0.88	0.75	0.65	0.59	0.54	0.49	0.41

 $I_T$  = Trip current: minimum current at which the device will always trip at 25 °C still air reflow soldering of 260 °C for 20 sec.

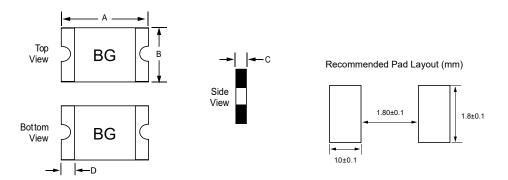
 $V_{\text{max}}$  = Maximum continuous voltage device can withstand without damage at rated current

 $I_{max}$  = Maximum fault current device can withstand without damage at rated voltage.

 $T_{\text{trip}}$  = Maximum time to trip(s) at assigned current reflow soldering of 260  $^\circ$  for 20 sec.  $P_{\text{dyp}}$  = Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

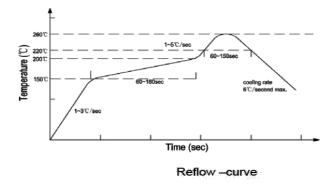
R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state.

#### **Dimensions**



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Part Number	Min	Max	Min	Max	Min	Max	Min
SRF1206P075/16	3.00	3.60	1.50	1.90	0.50	1.00	0.10

#### **Solder Reflow Recommendation**



Recommended reflow methods:IR,hot air oven ,nitrogen oven

Devices can be cleaned using standard industry methods and solvents.

#### NOTE:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame

# **Packaging Options**

Part Number	Quantity
SRF1206P075/16	3,500pcs

Reel packaging per EIA-481-1 standard

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